

IN THE CLAIMS

Please amend the claims as follows:

1. (Previously Presented) A method of forming a package, comprising:
placing a film against a flip-chip assembly, wherein the film includes a tacky film, wherein the flip-chip assembly includes a die, an electrical connection, and a mounting substrate;
underfilling the die with underfill material;
curing the underfill material; and
after beginning curing the underfill material, removing the film, wherein after beginning curing the underfill material and removing the film, curing includes heating the package in a curing oven under conditions to cause the tacky film to release from the flip-chip assembly.
2. (Canceled).
3. (Previously Presented) The method according to claim 1, wherein the film includes a tacky film, and wherein curing the underfill material is carried out under heat that causes the tacky film to release from the flip-chip assembly.
- 4 -6. (Canceled)
7. (Previously Presented) The method according to claim 1, wherein after beginning curing the underfill material and removing the film, curing includes:
heating the package in the curing oven under conditions to cause the tacky film to release from the flip-chip assembly, wherein heating includes a first temperature ramp to a temperature range from about 100° C to about 180° C, a temperature hold at a temperature in this range, a second temperature ramp to a temperature range from about 140° C to about 260° C, and cooling.

8. (Previously Presented) The method according to claim 1, wherein after beginning curing the underfill material and removing the film, curing includes:

heating the package in the curing oven under conditions to cause the tacky film to release from the flip-chip assembly, wherein heating includes a single step temperature ramp to a temperature in a range from about 140° C to about 240° C;

and

cooling.

9-26. (Canceled)